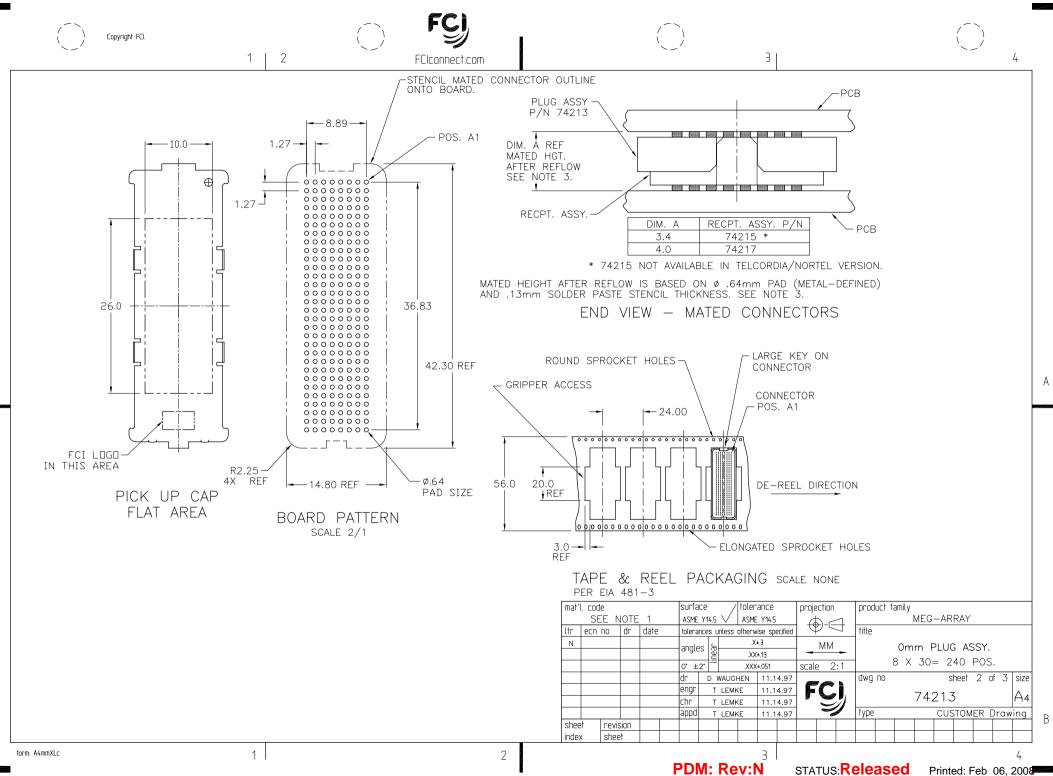


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FC

NOTES:

1.)<u>M</u>AT'L:

HOUSING: LCP CONTACT: COPPER ALLOY

PLATING

CONTACT: (SEE TABLE ON SHEET1) SOLDER BALL: (SEE TABLE ON SHEET1) EUTECTIC SnPb OR LEAD FREE 95.5Sn/4Ag/0.5Cu

- 2.) SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- (3.)MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- (4.) PLATING FOR -2XX SERIES DASH NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).
- (5) FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- (6.) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

1

mat'l. code SEE NOTE 1					surface tolerance ASME Y14.5 ASME Y14.5						projection			prod	product family								
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STATUS: Released Printed: Feb 06, 2008

PDM: Rev:N

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